

Heat-shrinkable films for packaging of vessels - moulded from resin compsns. contg. polypropylene resins and plasticiser.

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Patent Family

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JP 8034862	A		7	C08J-005/18	

Abstract:

JP 8034862 A

Heat-shrinkable films are moulded from resin compsns.contg. 100 pts.wt. of (A) polypropylene (PP) resins having a Mw of 80000-500000 and showing elution of < 5 wt.% (of all PP resin amt.) of resins at 0 deg.C and 0-20deg. C when determined by the Cross fractionation method, elution of 8-30 wt.% of resins at 20-70deg. C and elution of 70-95 wt.% of resins at 70-110deg. C and 5-60 pts. (B) plasticisers.

USE - The films are used for shrink packaging of vessels.

ADVANTAGE - The films are free from plasticiser-migration on the surface, sweat-out, loss of clarity and turbidity. They shrink at a heat-shrinkage rate of at least 20% at nearly 80 deg.C. They have small specific gravities and, when used for shrink-packaging of vessels, are sepd. and recovered easily.

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